



1.8 SEC

先進封裝協作型技術團隊

透過高度協作能力，讓不同體系客戶都能成功

C SUN 志聖工業

2026 Q2 Investor's meeting

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+ Alliance

Cross Holding Structure



G2C+ Alliance: The Platform Advantage

Control (東捷)

- Laser Application (雷射應用)
- Sputtering & Dry Etching (真空濺鍍 & 乾蝕刻)

GMM (均華)

- Die Attach (黏晶)
- Chip Sorter (揀晶)

2,400+

聯盟總人數
(Total Alliance Workforce)

900+

研發人員
(R&D Personnel)

CSun (志聖)

- Thermal (熱)
- Bonder (壓合)
- Lamination (貼膜)
- Wet Process (濕製程)
- Peeling (撕膜)
- UV/Plasma (光/電漿)

GPM (均豪)

- AOI (檢測)
- Metrology (量測)
- Grinding (研磨)
- Polishing (拋光)



快速協作網路 (Co-development Network)

建立在地零時差 (Zero-time-difference) 支援機制：就近服務大廠客戶，確保高階製程設備穩定運行與聯合開發。



ZERO-TIME DEVELOPMENT SYNC

生產腹地 (Production Resilience)

整合台南南科與樹谷的萬坪廠房：為聯盟提供高度靈活的巨型自動化與組裝產線空間。



AUTOMATION FLEXIBILITY TELEMETRY



AI賽道上的專業協作團隊

連續獲得冠軍車隊肯定



2023:
Excellent Production Support
(卓越量產支援)



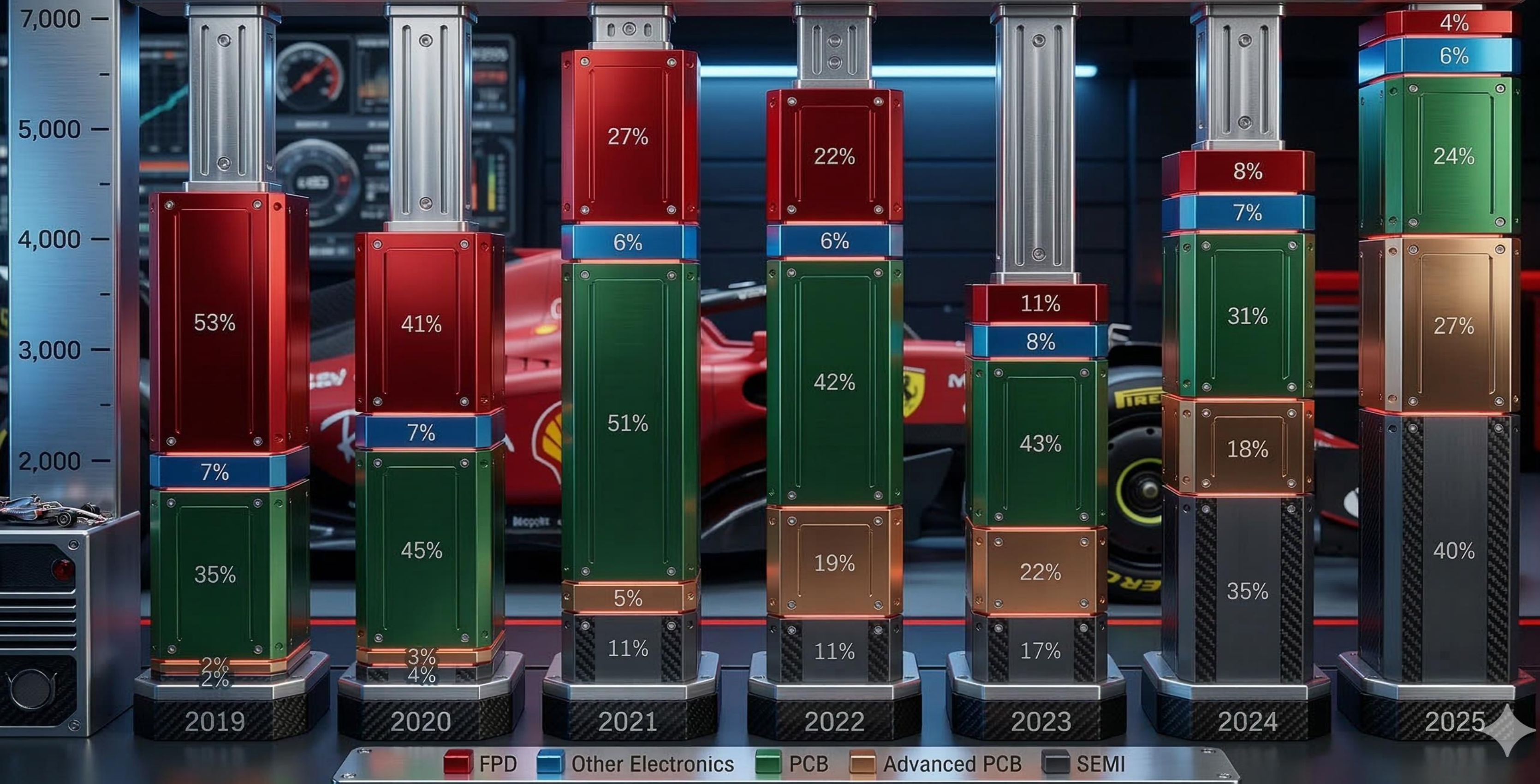
2024:
Outstanding Improvement
(傑出持續改善)



2025:
Excellent Production Support
(卓越量產支援)



REVENUE COMPOSITION (2019-2025)



2025 年財務亮點： 結構轉型與獲利創新高

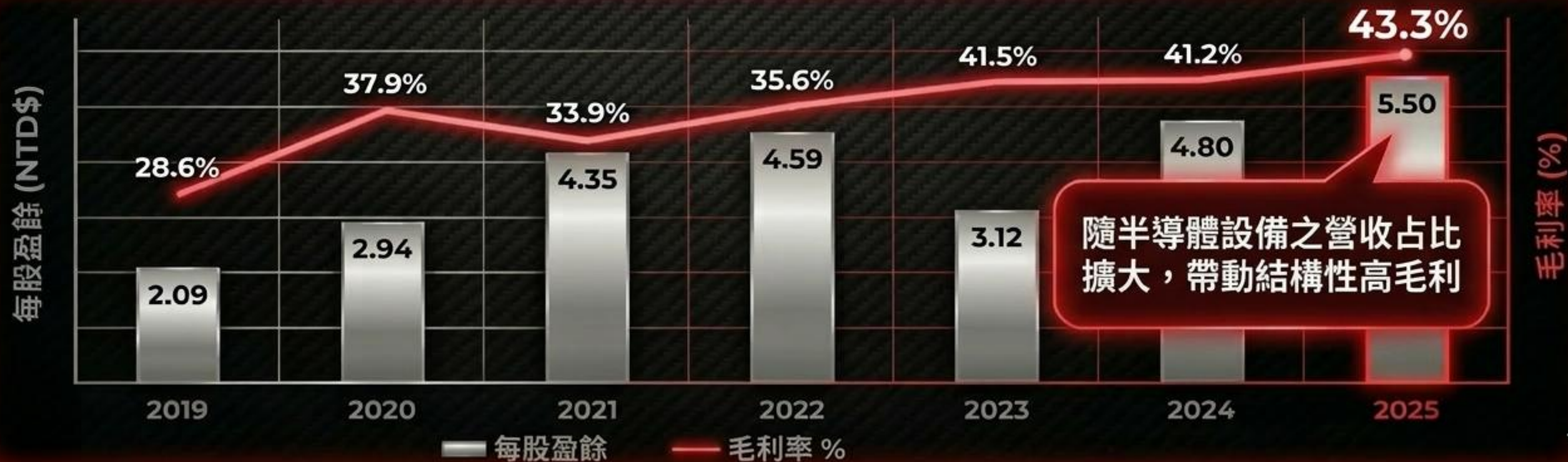
2025 年營收

NT\$ 61 億元

創歷史新高

2025 每股盈餘 (EPS)

NT\$ 5.50 元



2026 年度開局：累計營收創歷史新高

季增率
+29.5%

QoQ

22.62 億
新台幣

YoY

年增率
+72.8%

客戶的資本支出（CAPEX）持續流入，為未來成長提供永續動能。

動態應對客戶的交機排程



TSMC, intel, GF
FOUNDRY ACCESS TRACK

SoIC

InFO

EMIB

X-CUBE

WMCM

TSMC | Intel | GF

OSAT

AI substrate & HDI

AI SUBSTRATE & HDI
ACCESS TRACK

ABF

SAP

HDI

mSAP

OSAT
ACCESS TRACK

Adv. PLP

SoIC

InFO

FlipChip

FoCoS

FoPLP

CoWoS

CoWoS

CoWoP

CoWoP

CoWoS

Advanced Packaging
GRAND CIRCUIT

GRAND CIRCUIT

mSAP

C SUN & G2C+

透過策略演進驅動成長

維修站與共同起跑線

能量注入

技術檢查

零件

維修團隊：
C SUN & G2C+

引擎 I：
晶圓代工 2.0 全球化
全球化晶圓代工賽道

引擎 II：
AI 驅動的製程多元化
AI 製程賽道

引擎 III：
先進 PCB 與區域移轉
IC 載板 PCB 賽道

德國

晶圓廠
+fab

日本

晶圓廠
+fab

美國亞利桑那州

晶圓廠
+fab

全球化移轉

C SUN
資本支出獎

FOPLP
HBM
整合

AI
複雜度
驅動多元化

ASP (平均售價) 升級 → 獲利能力

東南亞區域
移轉

泰國
PCB

越南

技術藍圖：全方位製程覆蓋

Technology Roadmap: Full Spectrum Coverage



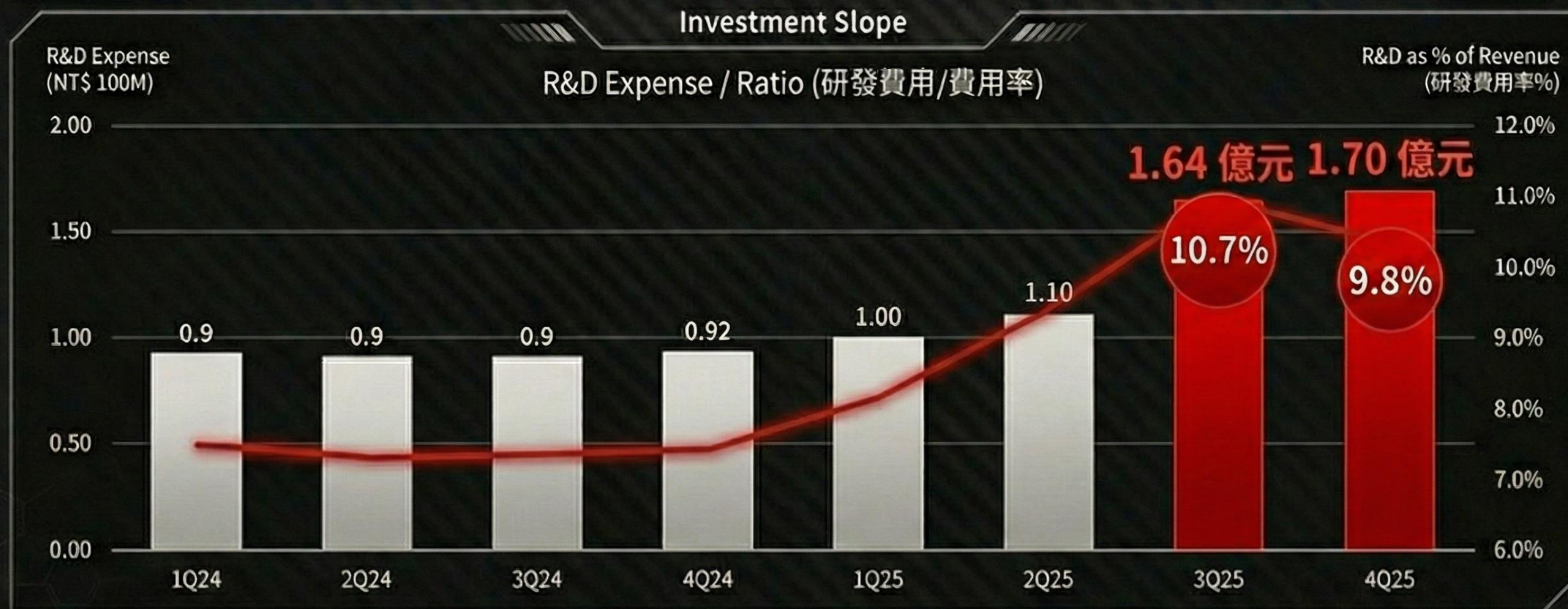
不僅掌握現有先進製程紅利，更已佈局未來 3 年 新製程需求

研發資源配置與技術升級

R&D Resource Allocation & Tech Upgrade

先進封裝產業鏈新世代製程與設備升級

Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain



技術升級期的投入將支持未來3-5年成長動能

築巢引鳳：研發中心與全球擴張

18.2 億 NTD

打造研發中心，為多元
前瞻設備開發奠定基礎。

USA

台中水湳研發中心

(Taichung Shuinan R&D Center)

The Innovation Hub

精科二廠

(Jingke Plant 2)

Capacity Expansion

Japan

14.8 億 NTD

購置廠房與設施，
確保未來產能無虞。

F1 先進封裝大賽

Foundry 主賽道

CoWoS / SoIC / WMCM



OSAT 賽道

PLP / oS / Bumping / CoW / EMIB



AI載板多層板賽道

IC Substrate / HDI

